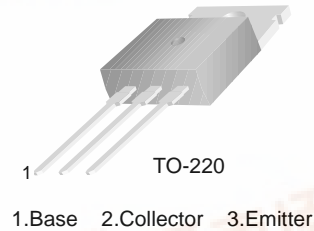




KSD363

B/W TV Horizontal Deflection Output

- Collector-Base Voltage : $V_{CBO}=300V$
- Collector Current : $I_C=6A$
- Collector Dissipation : $P_C=40W(T_C=25^{\circ}C)$



NPN Epitaxial Silicon Transistor

Absolute Maximum Ratings $T_C=25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Value	Units
V_{CBO}	Collector-Base Voltage	300	V
V_{CEO}	Collector-Emitter Voltage	120	V
V_{EBO}	Emitter-Base Voltage	8	V
I_C	Collector Current	6	A
P_C	Collector Dissipation ($T_C=25^{\circ}C$)	40	W
T_J	Junction Temperature	150	$^{\circ}C$
T_{STG}	Storage Temperature	- 55 ~ 150	$^{\circ}C$

Electrical Characteristics $T_C=25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
BV_{CBO}	Collector-Base Breakdown Voltage	$I_C=1mA, I_E=0$	300			V
BV_{CEO}	Collector-Emitter Breakdown Voltage	$I_C=20mA, I_B=0$	120			V
BV_{EBO}	Emitter-Base Breakdown Voltage	$I_E=1mA, I_C=0$	8			V
I_{CBO}	Collector Cut-off Current	$V_{CB}=250V, I_E=0$			1	mA
h_{FE}	DC Current Gain	$V_{CE}=5V, I_C=1A$	40		240	
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C=1A, I_B=0.1A$			1	V
$V_{BE(sat)}$	Base-Emitter Saturation Voltage	$I_C=1A, I_B=0.1A$			1.5	V
f_T	Current Gain Bandwidth Product	$V_{CE}=5V, I_C=0.5A$		10		MHz

h_{FE} Classification

Classification	R	O	Y
h_{FE}	40 ~ 80	70 ~ 140	120 ~ 240

Typical Characteristics

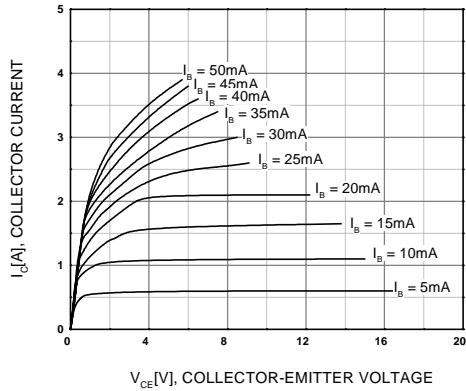


Figure 1. Static Characteristic

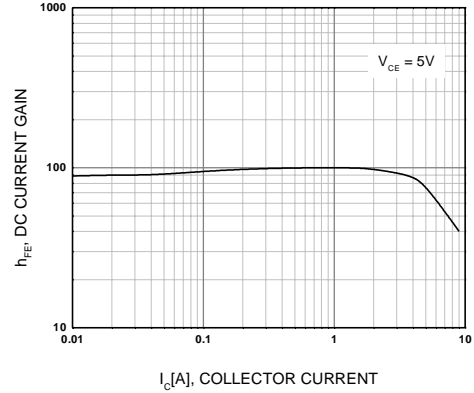


Figure 2. DC current Gain

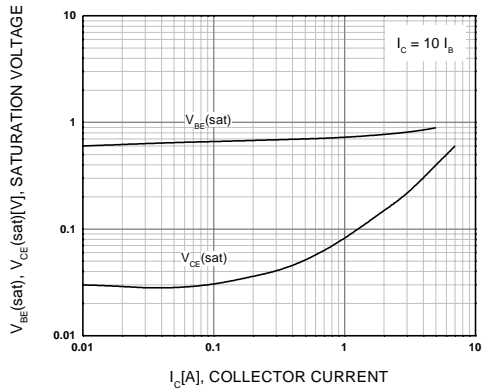


Figure 3. Base-Emitter Saturation Voltage
Collect-Emmitter Saturation Voltage

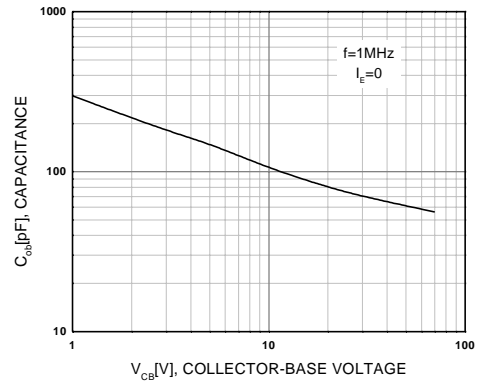


Figure 4. Collector Output Capacitance

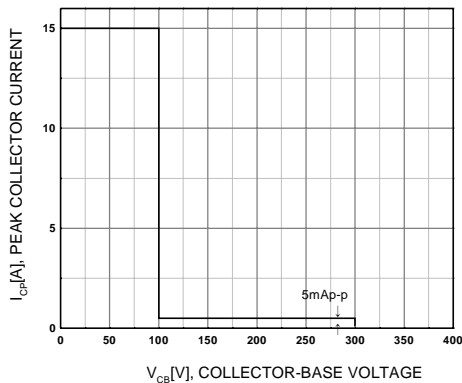


Figure 5. Safe Operating (On Horizontal
Deflection Output Circuit)

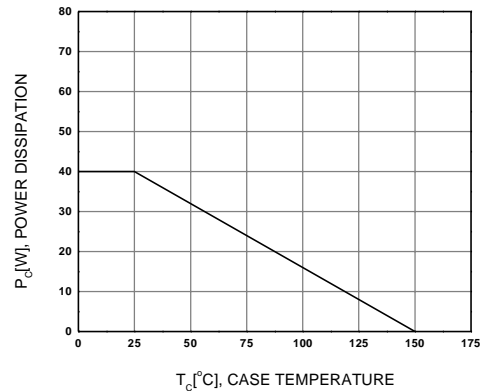


Figure 6. Power Derating

Technical drawing of a 2.54TYP connector showing front, side, and top views with dimensions in millimeters.

Front View Dimensions:

- Overall width: 9.90 ± 0.20
- Width of central section: (8.70)
- Top hole diameter: $\varnothing 3.60 \pm 0.10$
- Top hole offset from left edge: 1.30 ± 0.10
- Top hole offset from right edge: 2.80 ± 0.10
- Height of top section: 1.30 ± 0.10
- Height of middle section: 9.20 ± 0.20
- Height of bottom section: 13.08 ± 0.20
- Height of bottom section (alternative): (1.46)
- Height of bottom section (alternative): (1.00)
- Height of bottom section (alternative): (3.00)
- Height of bottom section (alternative): (3.70)
- Height of bottom section (alternative): 15.90 ± 0.20
- Height of bottom section (alternative): 18.95 MAX.
- Height of bottom section (alternative): 10.08 ± 0.30
- Height of bottom section (alternative): 1.27 ± 0.10
- Height of bottom section (alternative): 1.52 ± 0.10
- Height of bottom section (alternative): 0.80 ± 0.10
- Height of bottom section (alternative): 2.54 TYP
- Height of bottom section (alternative): $[2.54 \pm 0.20]$

Side View Dimensions:

- Overall height: 4.50 ± 0.20
- Height of top section: $1.30^{+0.10}_{-0.05}$
- Height of bottom section: $0.50^{+0.10}_{-0.05}$
- Height of bottom section (alternative): 2.40 ± 0.20

Top View Dimensions:

- Overall width: 10.00 ± 0.20

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